

Abstract

A method for the connection of electronic components, in which (a) a sandwich arrangement is provided, which comprises at least (a1) an electronic component 1, (a2) an electronic component 2, and (a3) a metal sintering preparation being situated between metal contact surfaces of the electronic components 1 and 2, and in which (b) the sandwich arrangement is being pressureless sintered, wherein the method takes place in an ambient gas atmosphere, and wherein an exchange of the ambient gas atmosphere is made within the course of the pressureless metal sintering process.